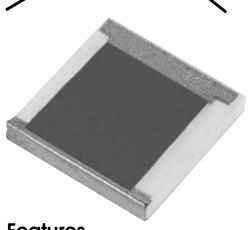


## Model RFP-375375-6X50-2

## F Power

# Chip Terminations 300 Watts, 50 Ω



#### **Features**

- DC 1.0 GHz
- 300 Watts
- **BeO Ceramic**
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

#### **General Specifications**

**Resistive Element:** Thick film

Substrate: Beryllium oxide ceramic

Terminals: Thick film silver

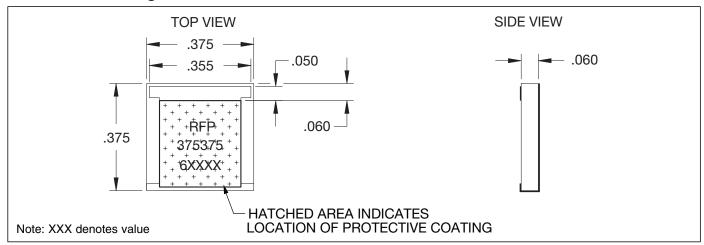
#### **Electrical Specifications**

**Resistance Value:** 50 ohms, ±2% Frequency Range: DC - 1.0 GHz Power: 300 Watts V.S.W.R.: 1.25:1

Notes: Tolerance is ±.010, unless otherwise specified. Operating temperature is -55°C to +150°C (see chart). Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions are in

Specifications subject to change without notice.

#### **Outline Drawing**



VER. 12/5/01



Available on Tape and Reel for Pick and Place Manufacturing.

Sales Desk USA: Voice: (800) 544-2414 Fax: (315) 432-9121

Sales Desk Europe: Voice: (+44) 23 92 232392 Fax: (+44) 23 92 251369

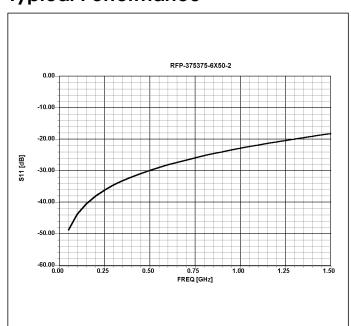


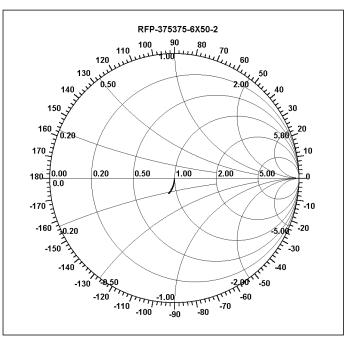
## Model RFP-375375-6X50-2



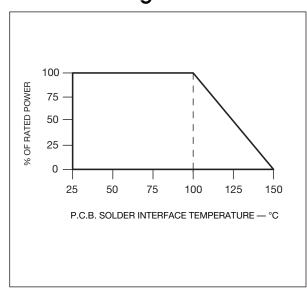


### Typical Performance

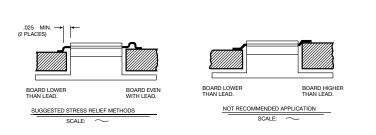




#### **Power Derating**



### **Suggested Mounting Procedures**



- 1. Make sure that the devices are mounted on flat surfaces (.001" under the device) to optimize the heat transfer.
- 2. Position device on mounting surface and solder in place using an indalloy type or a 60/40 type solder.
- 3. Solder leads in place using a 60/40 type solder with a controlled temperature iron (700°F).







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